

# Hyperfast Rectifier, 30 A FRED Pt®



TO-247AC 2L

## FEATURES

- Hyperfast recovery time
- Low forward voltage drop
- 175 °C operating junction temperature
- Low leakage current
- Single diode device
- Designed and qualified according to JEDEC®-JESD 47
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

## LINKS TO ADDITIONAL RESOURCES



3D Models

## PRIMARY CHARACTERISTICS

$I_{F(AV)}$	30 A
$V_R$	600 V
$V_F$ at $I_F$	1.34 V
$t_{rr}$ typ.	See Recovery table
$T_J$ max.	175 °C
Package	TO-247AC 2L
Circuit configuration	Single

## DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS, inverters or as freewheeling diodes.

Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

## MECHANICAL DATA

**Case:** TO-247AC 2L

Molding compound meets UL 94 V-0 flammability rating

**Terminals:** matte tin plated leads, solderable per J-STD-002

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		600	V
Average rectified forward current	$I_{F(AV)}$	$T_C = 116\text{ °C}$	30	A
Non-repetitive peak surge current	$I_{FSM}$	$T_J = 25\text{ °C}$ , $t_p = 10\text{ ms}$	300	
Operating junction and storage temperatures	$T_J$ , $T_{Stg}$		-65 to +175	°C

## ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}$ , $V_R$	$I_R = 100\text{ }\mu\text{A}$	600	-	-	V
Forward voltage	$V_F$	$I_F = 30\text{ A}$	-	2.0	2.6	
		$I_F = 30\text{ A}$ , $T_J = 150\text{ °C}$	-	1.34	1.75	
Reverse leakage current	$I_R$	$V_R = V_R$ rated	-	0.3	50	$\mu\text{A}$
		$T_J = 150\text{ °C}$ , $V_R = V_R$ rated	-	60	500	
Junction capacitance	$C_T$	$V_R = 600\text{ V}$	-	33	-	pF
Series inductance	$L_S$	Measured lead to lead 5 mm from package body	-	3.5	-	nH

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ }^{\circ}\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1.0\text{ A}$ , $dI_F/dt = 50\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	28	35	ns
		$T_J = 25\text{ }^{\circ}\text{C}$	-	31	-	
		$T_J = 125\text{ }^{\circ}\text{C}$	-	77	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	3.5	-	A
		$T_J = 125\text{ }^{\circ}\text{C}$	-	7.7	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^{\circ}\text{C}$	-	65	-	nC
		$T_J = 125\text{ }^{\circ}\text{C}$	-	345	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J, T_{Stg}$		-65	-	175	$^{\circ}\text{C}$
Thermal resistance, junction to case per leg	$R_{thJC}$		-	0.5	0.9	$^{\circ}\text{C}/\text{W}$
Thermal resistance, junction to ambient per leg	$R_{thJA}$	Typical socket mount	-	-	40	
Thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, flat, smooth and greased	-	0.4	-	
Weight			-	6.0	-	g
Mounting torque			6.0 (5.0)	-	12 (10)	kgf · cm (lbf · in)
Marking device		Case style TO-247AC 2L	30EPH06			

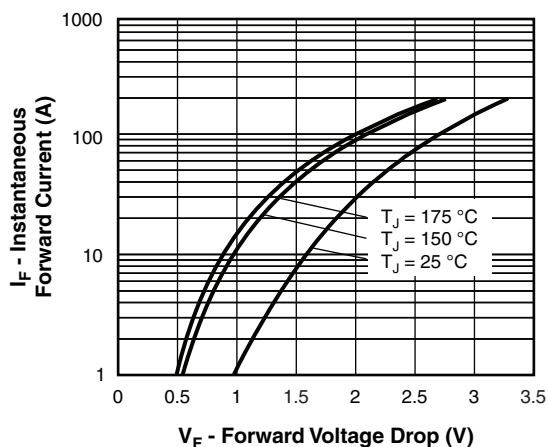


Fig. 1 - Typical Forward Voltage Drop Characteristics

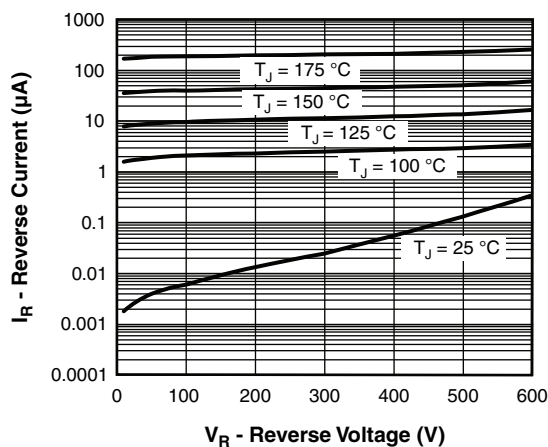


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

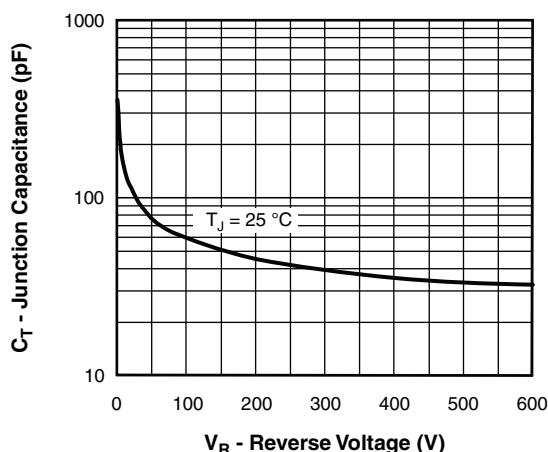


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

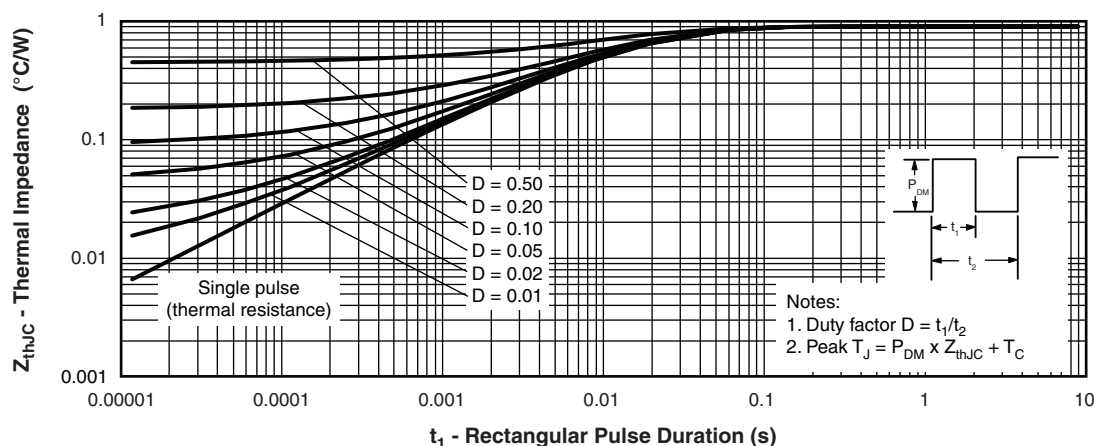
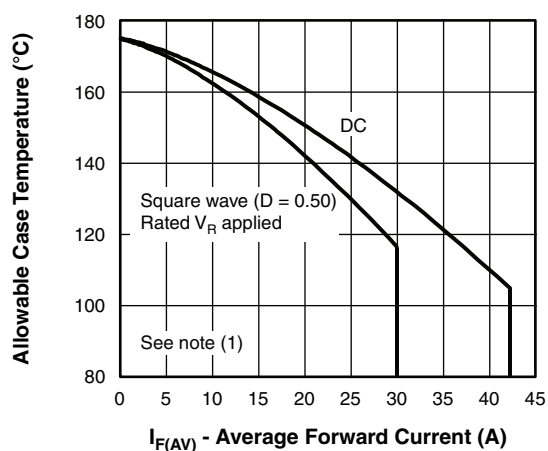

Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

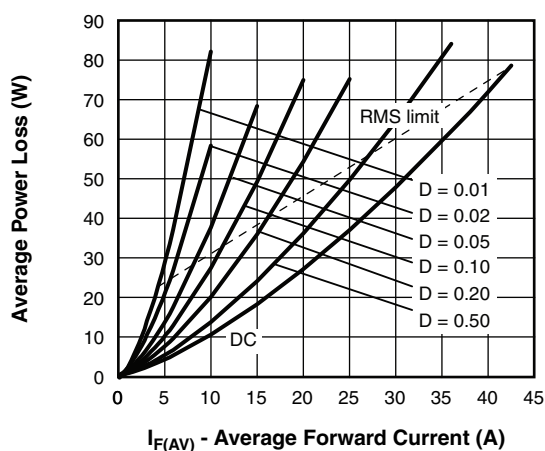


Fig. 6 - Forward Power Loss Characteristics

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;  
 $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);  
 $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

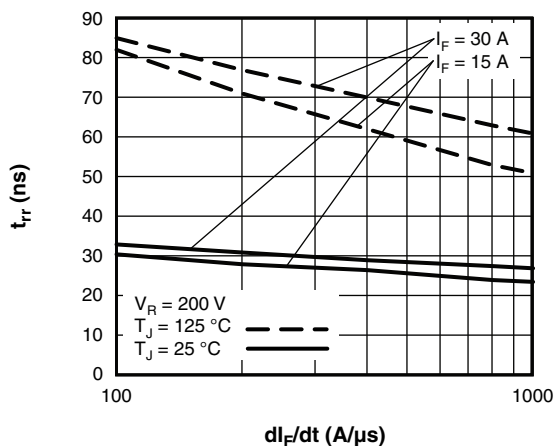
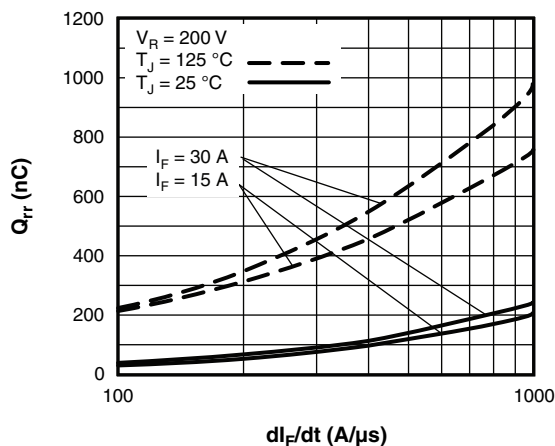
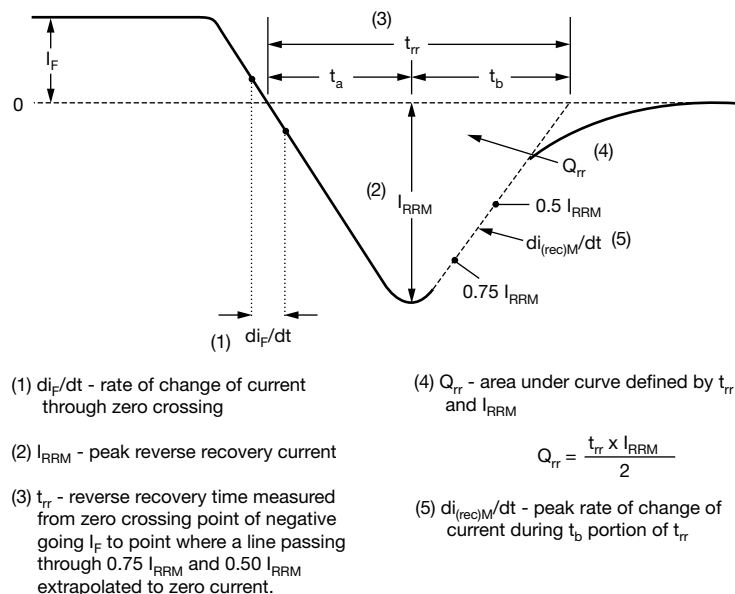

Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$ 

Fig. 8 - Typical Stored Charge vs.  $di_F/dt$ 


Fig. 9 - Reverse Recovery Waveform and Definitions

**ORDERING INFORMATION TABLE**

Device code	VS-	30	E	P	H	06	-N3
	1	2	3	4	5	6	7
	1	-	Vishay Semiconductors product				
	2	-	Current rating (30 = 30 A)				
	3	-	Circuit configuration: E = single diode				
	4	-	Package: P = TO-247AC				
	5	-	H = hyperfast recovery				
	6	-	Voltage rating (06 = 600 V)				
	7	-	Environmental digit: -N3 = halogen-free, RoHS-compliant, and totally lead (Pb)-free				

**ORDERING INFORMATION** (Example)

PREFERRED P/N	QUANTITY PER T/R	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-30EPH06-N3	25	500	Antistatic plastic tube

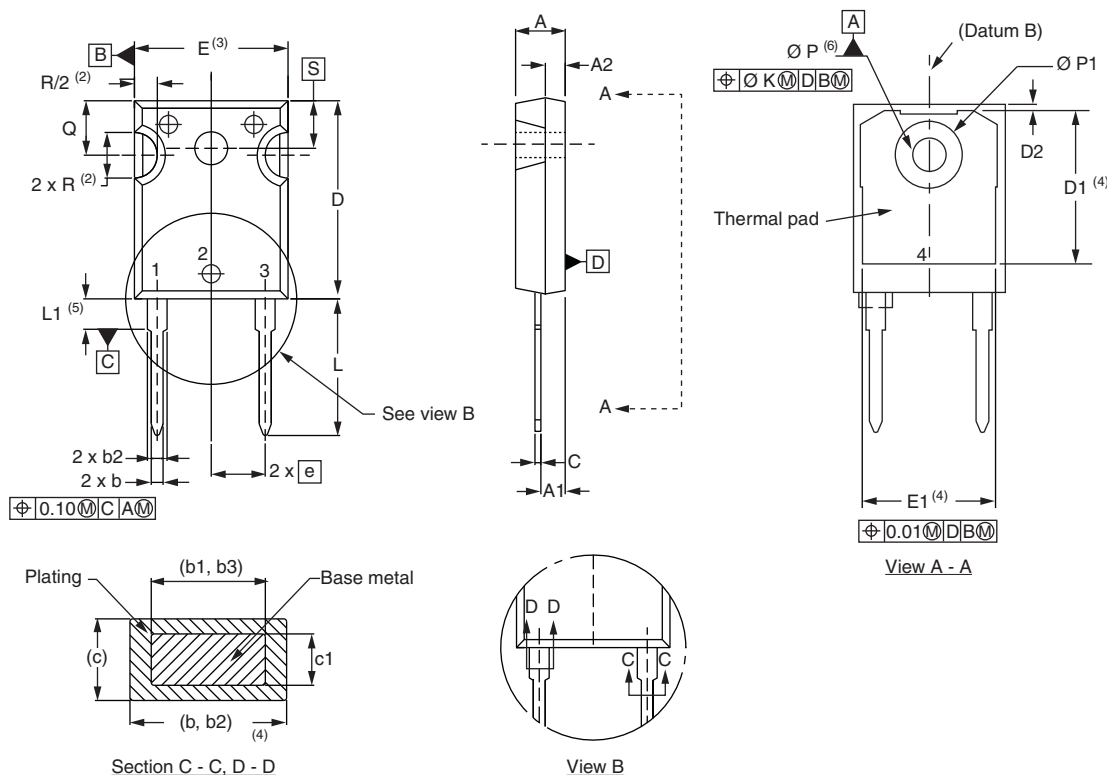
**LINKS TO RELATED DOCUMENTS**

Dimensions	<a href="http://www.vishay.com/doc?96144">www.vishay.com/doc?96144</a>
Part marking information	<a href="http://www.vishay.com/doc?95648">www.vishay.com/doc?95648</a>
SPICE model	<a href="http://www.vishay.com/doc?96573">www.vishay.com/doc?96573</a>



## TO-247AC 2L

DIMENSIONS in millimeters and inches



SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
A	4.65	5.31	0.183	0.209	
A1	2.21	2.59	0.087	0.102	
A2	1.17	1.37	0.046	0.054	
b	0.99	1.40	0.039	0.055	
b1	0.99	1.35	0.039	0.053	
b2	1.65	2.39	0.065	0.094	
b3	1.65	2.34	0.065	0.092	
c	0.38	0.89	0.015	0.035	
c1	0.38	0.84	0.015	0.033	
D	19.71	20.70	0.776	0.815	3
D1	13.08	-	0.515	-	4
D2	0.51	1.35	0.020	0.053	

SYMBOL	MILLIMETERS		INCHES		NOTES
	MIN.	MAX.	MIN.	MAX.	
E	15.29	15.87	0.602	0.625	3
E1	13.46	-	0.53	-	
e	5.46 BSC		0.215 BSC		
Ø K	0.254		0.010		
L	14.20	16.10	0.559	0.634	
L1	3.71	4.29	0.146	0.169	
Ø P	3.56	3.66	0.14	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		

## Notes

- (1) Dimensioning and tolerancing per ASME Y14.5M-1994
- (2) Contour of slot optional
- (3) Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body
- (4) Thermal pad contour optional with dimensions D1 and E1
- (5) Lead finish uncontrolled in L1
- (6) Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154")
- (7) Outline conforms to JEDEC® outline TO-247 with exception of dimension Q



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